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Route de Vinon-sur-Verdon - CS 90 046 - 13067 St Paul Lez Durance Cedex - France

To: Potential Suppliers

Ref: IO/MS/23/JGO/TCWS/CT12

Subject: Letter of Invitation for the Market Survey on “Supply of Baking Pumps and Main Flow Pumps”

Dear Madam/Sir,

The ITER Organization (IO) launches a Market Survey and requests information from companies having the interest, knowledge and capacity related to the **Supply of Baking Pumps and Main Flow Pumps**.

At this moment, the IO is preparing the budget baseline for TCWS Arrangement 5. Therefore, the main purpose of this Market Survey is to get from potential suppliers a non-binding cost estimation for the supply in subject. The target uncertainty of the estimation should be within +/-15%.

Please note that this is not a Call for Nomination request, and the purpose of this survey is not to access and evaluate the capacity of your company. Therefore, we would appreciate very much if you will provide open and frank feedback, which will help the IO to better understand the real situation of the industry.

You will find enclosed:

- Cover Sheet Document for Arrangement 5 Cost Evaluation (Annex I);
- Arrangement 5 Equipment Summary (Annex II) including:
 - PHBD Baking Pump (26PHBD-PL-1900)
 - PHNB – Main Flow Pump (26PHNB-PL-3010/3020)
- Cost Estimation Template and Questionnaire (Annex III).

With this letter, we invite all potential companies, institutions or entities from ITER Member States to participate to this Market Survey. We also kindly invite the Domestic Agencies to publish this Market Survey on their websites or through other advertising methods, which will help to retrieve the requested information from a maximum of potential suppliers.

Please return a completed cost estimation and questionnaire using the template of Annex III, **no later than 5 May 2023**, to the following email address Jingyu.Gao@iter.org .

Thanks in advance for your participation and co-operation.

Yours faithfully,

William De Cat
Section Leader
Construction, Assembly and Logistics Section